

ABSTRACT

POLISHING APPARATUS

Disclosed is a polishing apparatus that polishes a substrate by causing the substrate to be in slide contact with a polishing pad. The polishing apparatus includes a pad temperature control mechanism configured to control a surface temperature of the polishing pad, which includes a pad contact member that comes in contact with the surface of the polishing pad and a liquid supply system configured to supply a temperature-controlled liquid to the pad contact member. The pad contact member includes a liquid flow path therein, and the liquid flow path communicates with a liquid inlet and a liquid outlet connected to the liquid supply system. At least one planar baffle is disposed in the liquid flow path, and the baffle has a space therein.

[Representative Drawing] FIG. 4